

PATENT
3313-1099P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: CHANG, Shu-Ming et al Conf.:
Appl. No.: NEW Group:
Filed: January 29, 2004 Examiner:
For: WAFER LEVEL CHIP SCALE PACKAGING
 STRUCTURE AND METHOD OF FABRICATING THE
 SAME

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

January 29, 2004

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

This amendment includes Amendments to the Specification and Remarks.